

Title (en)
MEMS CIRCUIT BOARD MODULE HAVING AN INTEGRATED PIEZOELECTRIC STRUCTURE, AND ELECTROACOUSTIC TRANSDUCER ARRANGEMENT

Title (de)
MEMS-LEITERPLATTENMODUL MIT INTEGRIERTER PIEZOELEKTRISCHER STRUKTUR SOWIE SCHALLWANDLERANORDNUNG

Title (fr)
MODULE À CARTE DE CIRCUIT IMPRIMÉ MEMS À STRUCTURE PIÉZOÉLECTRIQUE INTÉGRÉE ET ENSEMBLE TRANSDUCTEUR ACOUSTIQUE

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Abstract (en)
[origin: WO2017055012A1] The invention relates to a MEMS circuit board module (1) for an electroacoustic transducer arrangement (2) for generating and/or detecting sound waves in the audible wavelength spectrum, comprising a circuit board (4) and a multilayer piezoelectric structure (5) that allows a membrane (6), which is provided for this purpose, to vibrate and/or detects vibrations of the membrane (6). According to the invention, the multilayer piezoelectric structure (5) is connected directly to the circuit board (4). The invention further relates to an electroacoustic transducer arrangement (2) comprising a MEMS circuit board module (1) of this type as well as to a method for manufacturing the MEMS circuit board module (1) and the electroacoustic transducer arrangement (2).

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